

# **PNE200100CPE**

# 200 V, 2 x 5 A dual common cathode hyperfast recovery rectifier

9 September 2021

Product data sheet

## 1. General description

High power density, hyperfast switching time dual recovery rectifier in common cathode configuration with high-efficiency planar technology, encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

#### 2. Features and benefits

Reverse voltage: V<sub>R</sub> ≤ 200 V

Forward current: I<sub>F</sub> ≤ 5 A (per diode)

Switching time: t<sub>rr</sub> ≤ 30 ns
 Pt doped life time control

Low inductance

- . . . . . .

Power and flat lead SMD plastic package

Package height typical 0.95 mm

High power capability due to clip-bond technology

· Planar die design

AEC-Q101 qualified

## 3. Applications

- · General-purpose rectification
- Hyperfast switching
- Solenoid control
- Piezo injection
- Freewheeling applications

#### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit	
Per diode (ı	Per diode (unless otherwise specified)							
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; f = 20 kHz; square wave; T <sub>sp</sub> $\leq$ 155 °C		-	-	5	Α	
$V_{RRM}$	repetitive peak reverse voltage	T <sub>j</sub> = 25 °C		-	-	200	V	
V <sub>R</sub>	reverse voltage			-	-	200	V	
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 5 A; T <sub>j</sub> = 25 °C	[1]	-	880	950	mV	
		I <sub>F</sub> = 5 A; T <sub>j</sub> = 125 °C	[1]	-	740	840	mV	
I <sub>R</sub>	reverse current	V <sub>R</sub> = 200 V; T <sub>j</sub> = 25 °C	[1]	-	-	1	μΑ	
		V <sub>R</sub> = 200 V; T <sub>j</sub> = 125 °C	[1]	-	2	40	μΑ	

[1] Very short pulse, in order to maintain a stable junction temperature.



# 5. Pinning information

#### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode (diode 1)		CC
2	A2	anode (diode 2)	1	
3	CC	common cathode	3 CFP15B (SOT1289B)	A1 A2  aaa-030081

# 6. Ordering information

#### **Table 3. Ordering information**

Type number	Package							
	Name	Description	Version					
PNE200100CPE		plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; 5.8 x 4.3 x 0.95 mm body	SOT1289B					

# 7. Marking

#### Table 4. Marking codes

Type number	Marking code
PNE200100CPE	200E
	010C

# 8. Limiting values

#### **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC60134)

Symbol	Parameter	Conditions		Min	Max	Unit
Per diode (u	nless otherwise specified)					
$V_R$	reverse voltage	T <sub>j</sub> = 25 °C		-	200	V
$V_{RRM}$	repetitive peak reverse voltage			-	200	V
V <sub>R(RMS)lim</sub>	limiting RMS reverse voltage			-	140	V
I <sub>F</sub>	forward current	δ = 1; T <sub>sp</sub> ≤ 150 °C		-	7.1	А
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; f = 20 kHz; square wave; T <sub>sp</sub> ≤ 155 °C		-	5	A
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p$ = 8.3 ms; single half sine wave (applied at rated load condition); $T_{j(init)}$ = 25 °C		-	90	А
		$t_p$ = 8.3 ms; single half sine wave (applied at rated load condition); per device; $T_{j(init)}$ = 25 °C		-	170	А
Per device, o	one diode loaded				'	
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1]	-	1.66	W
			[2]	-	2.15	W
T <sub>j</sub>	junction temperature			-	175	°C
T <sub>amb</sub>	ambient temperature			-55	175	°C
T <sub>stg</sub>	storage temperature			-65	175	°C

<sup>[1]</sup> Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

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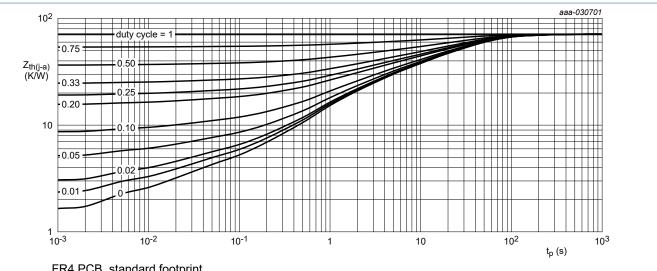
<sup>[2]</sup> Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

## 9. Thermal characteristics

**Table 6. Thermal characteristics** 

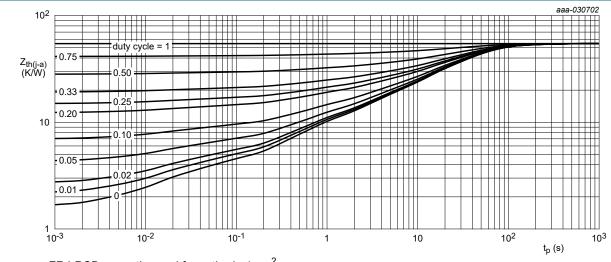
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Per device, one	Per device, one diode loaded						
R <sub>th(j-a)</sub>	thermal resistance from	in free air	[1]	-	-	90	K/W
	junction to ambient		[2]	-	=	70	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		[3]	-	-	7	K/W

- Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- Soldering point of cathode tab.



FR4 PCB, standard footprint

Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

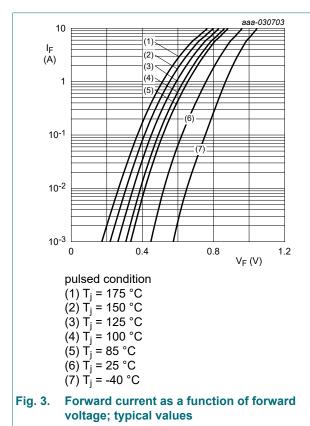
Transient thermal impedance from junction to ambient as a function of pulse duration; typical values Fig. 2.

## 10. Characteristics

**Table 7. Characteristics** 

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Per diode (	unless otherwise specified	)					
V <sub>(BR)R</sub>	reverse breakdown voltage	I <sub>R</sub> = 100 μA; T <sub>j</sub> = 25 °C	[1]	200	-	-	V
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 5 A; T <sub>j</sub> = 25 °C	[1]	-	880	950	mV
		I <sub>F</sub> = 5 A; T <sub>j</sub> = 125 °C	[1]	-	740	840	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 200 V; T <sub>j</sub> = 25 °C	[1]	-	-	1	μΑ
		V <sub>R</sub> = 200 V; T <sub>j</sub> = 125 °C	[1]	-	2	40	μΑ
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 4 V; f = 1 MHz; T <sub>j</sub> = 25 °C		-	60	-	pF
t <sub>rr</sub>	reverse recovery time step recovery	$I_F = 0.5 \text{ A}; I_R = 1 \text{ A}; I_{R(meas)} = 0.25 \text{ A};$ $T_j = 25 \text{ °C}$		-	12	30	ns
	reverse recovery time ramp recovery	$dI_F/dt = 50 \text{ A/}\mu\text{s}; I_F = 1 \text{ A}; V_R = 30 \text{ V};$ $T_j = 25 \text{ °C}$		-	19	-	ns
	reverse recovery time	$dI_F/dt = 100 A/\mu s; I_F = 1 A; V_R = 30 V;$		-	15	-	ns
I <sub>RM</sub>	peak reverse recovery current	T <sub>j</sub> = 25 °C		-	1	-	A
Q <sub>rr</sub>	reverse recovery charge			-	9	-	nC
$V_{FRM}$	peak forward recovery voltage	$I_F = 1 \text{ A}; \text{ d}I_F/\text{d}t = 50 \text{ A}/\mu\text{s}; T_j = 25 ^{\circ}\text{C}$		-	785	-	mV

[1] Very short pulse, in order to maintain a stable junction temperature.



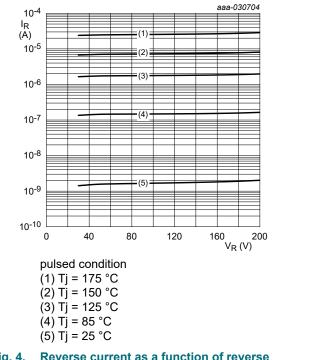


Fig. 4. Reverse current as a function of reverse voltage; typical values

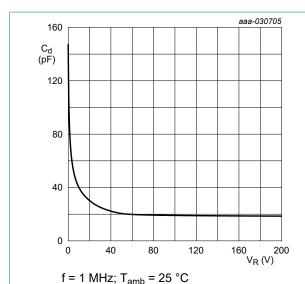
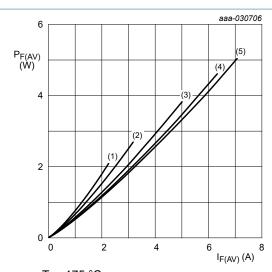
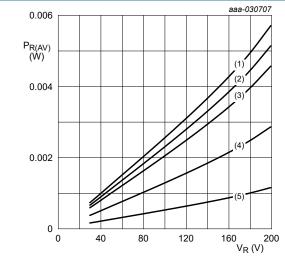


Fig. 5. Diode capacitance as a function of reverse voltage; typical values



 $T_j = 175 \,^{\circ}\text{C}$   $(1) \, \delta = 0.1$   $(2) \, \delta = 0.2$   $(3) \, \delta = 0.5$   $(4) \, \delta = 0.8$  $(5) \, \delta = 1; \, DC$ 

Fig. 6. Average forward power dissipation as a function of average forward current; typical values

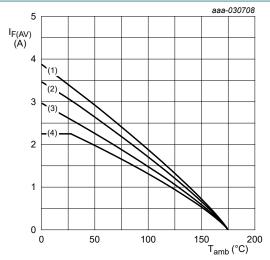


 $T_j = 175 \,^{\circ}\text{C}$ (1)  $\delta = 1$ ; DC (2)  $\delta = 0.9$ 

 $(3) \delta = 0.8$  $(4) \delta = 0.5$ 

 $(4) \delta = 0.3$  $(5) \delta = 0.2$ 

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

 $T_j = 175 \,{}^{\circ}\text{C}$ 

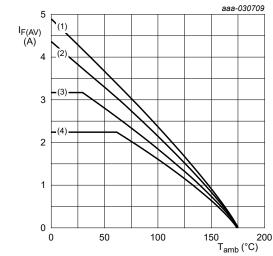
 $(1) \delta = 1$ ; DC

(2)  $\delta$  = 0.5; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

 $T_i = 175 \,{}^{\circ}\text{C}$ 

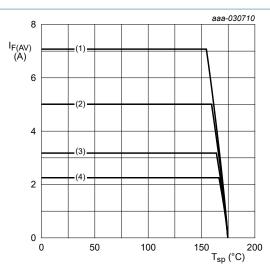
 $(1) \delta = 1; DC$ 

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Average forward current as a function of Fig. 9. ambient temperature; typical values



 $T_i = 175 \,{}^{\circ}\text{C}$ 

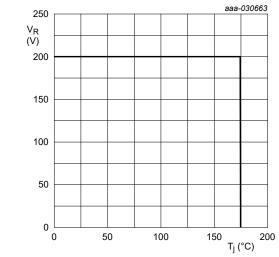
 $(1) \delta = 1; DC$ 

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

 $(4) \delta = 0.1$ ; f = 20 kHz

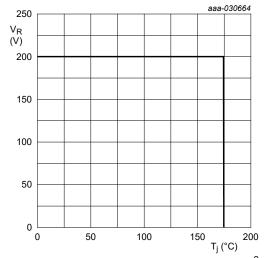
Fig. 10. Average forward current as a function of solder point temperature; typical values



FR4 PCB, standard footprint

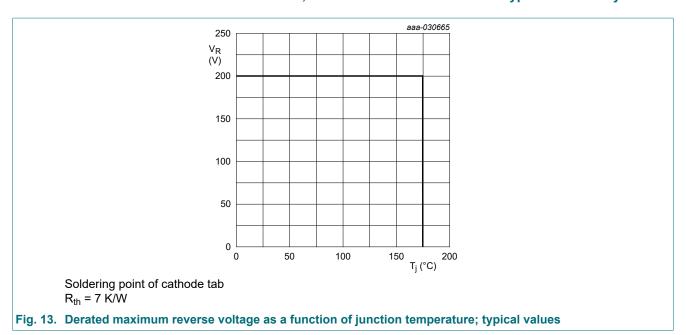
 $R_{th} = 90 \text{ K/W}$ 

of junction temperature; typical values

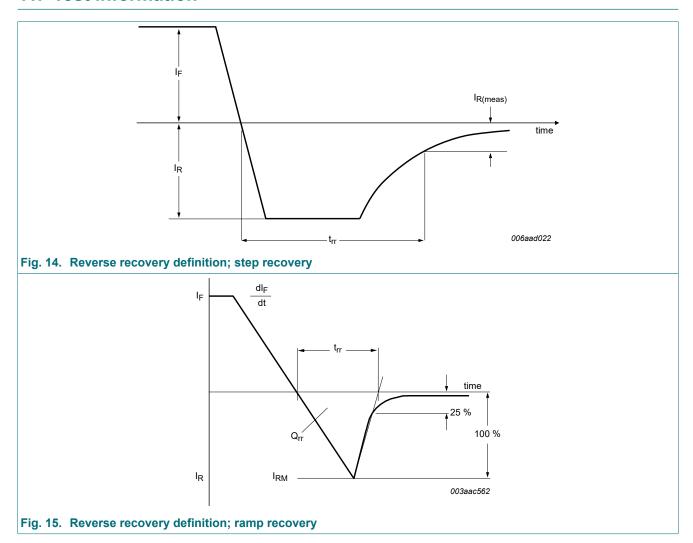


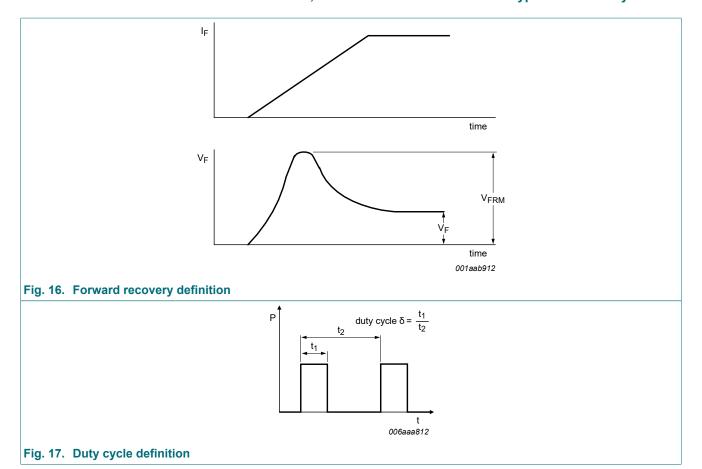
FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  $R_{th} = 70 \text{ K/W}$ 

Fig. 11. Derated maximum reverse voltage as a function | Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values



## 11. Test information





The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current

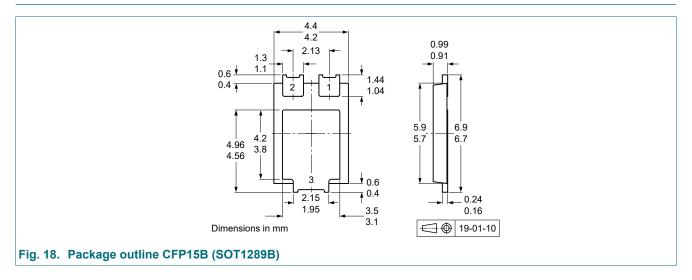
 $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_{M} \times \sqrt{\delta}$ 

with  $I_{\mbox{\scriptsize RMS}}$  defined as RMS current.

#### **Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

# 12. Package outline



## 13. Soldering

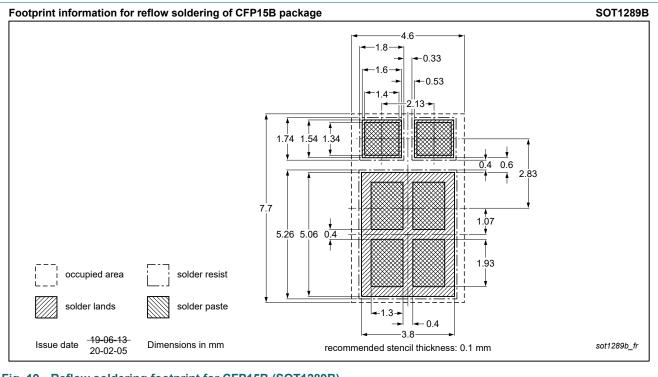


Fig. 19. Reflow soldering footprint for CFP15B (SOT1289B)

# 14. Revision history

#### **Table 8. Revision history**

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Data sheet ID	Release date	Data sheet status	Change notice	Supersedes		
PNE200100CPE v.4	20210909	Product data sheet	-	PNE200100CPE v.3		
Modifications:	Characteristics: Graph Fig. 4. revised (unlabeled curve removed); no technical ch					
PNE200100CPE v.3	20200214	Product data sheet	-	PNE200100CPE v.2		
PNE200100CPE v.2	20200127	Product data sheet	-	PNE200100CPE v.1		
PNE200100CPE v.1	20191219	Preliminary data sheet	-	-		

## 15. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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